

Overview of APEEM Thermal Control Research Projects

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*This presentation does not contain any
proprietary or confidential information*

Thermal Control Research Direction

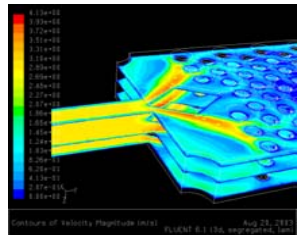
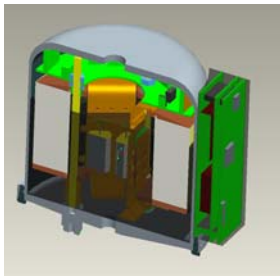
Meeting costs, specific power, power density, and efficiency targets while driving toward higher coolant temperatures :



- Motor R&D
 - Increasing speed (Reduce Size)
 - Innovative concepts to lower material and manufacturing costs
 - Eliminate need for boost converter
 - Reduce stress on battery during high loads

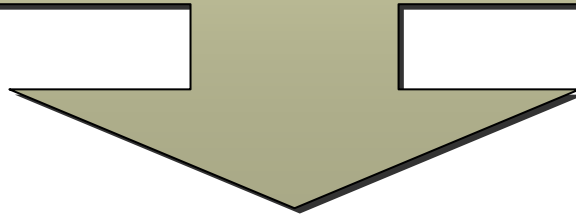
- Power Electronics R&D
 - Reduce size and cost of capacitor via topology and capacitor improvement
 - Increase temperature rating
 - Reduce and dissipate heat more effectively
 - Reduce parts count by integrating functionality

- Thermal Control R&D
 - Enable cost and power density targets through the elimination of the separate coolant loop and development of enhanced heat transfer technologies
 - Parallel paths will focus on the use of engine coolant at 105°C and the development of air cooling technologies



Technical Requirements

- **Thermal control is a critical factor in PEEM performance**
- **Today's HEVs: dedicated 70°C PEEM cooling system**
 - Cost is estimated at \$175 to consumer
- **PEEM target cost is \$440 for 55 kW system**
- **Current cooling system cost represents 40% of PEEM system cost target**



Conclusion – need to reduce coolant system cost

Primary focus on 105°C coolant and air cooling

Technical Approach – 105C engine coolant (T_c)

h

Enhance heat transfer coefficient

- jet/spray cooling
- surface enhancements

Q

Improve component/system efficiency

- Improved devices

A

Increase surface area

- fin shape optimization
- surface enhancements
- thermal spreading
- double-sided cooling

$$Q = h A (T_B - T_C)$$

$$Q = \frac{(T_H - T_B)}{R_{solder} + R_{DBC} + R_{TIM}}$$

$$Q = \dot{m} C_p (T_{out} - T_{in})$$

T_H

Increase maximum allowable temperature

- PE materials development

R

Reduce Thermal Resistance

- advanced TIM materials
- low R IGBT structure

Technical Approach – Air Cooling

Q

Improve component/system efficiency

- improved devices
- dynamic control of coolant

h

Enhance heat transfer coefficient

- micro-channel forced convection
- surface enhancements

A

Increase surface area

- fin shape optimization
- surface enhancements
- thermal spreading
- double-sided cooling

$$Q = h A (T_S - T_C)$$

$$Q = \frac{(T_H - T_B)}{R_{solder} + R_{DBC} + R_{TIM}}$$

$$Q = \dot{m} C_p (T_{out} - T_{in})$$

R

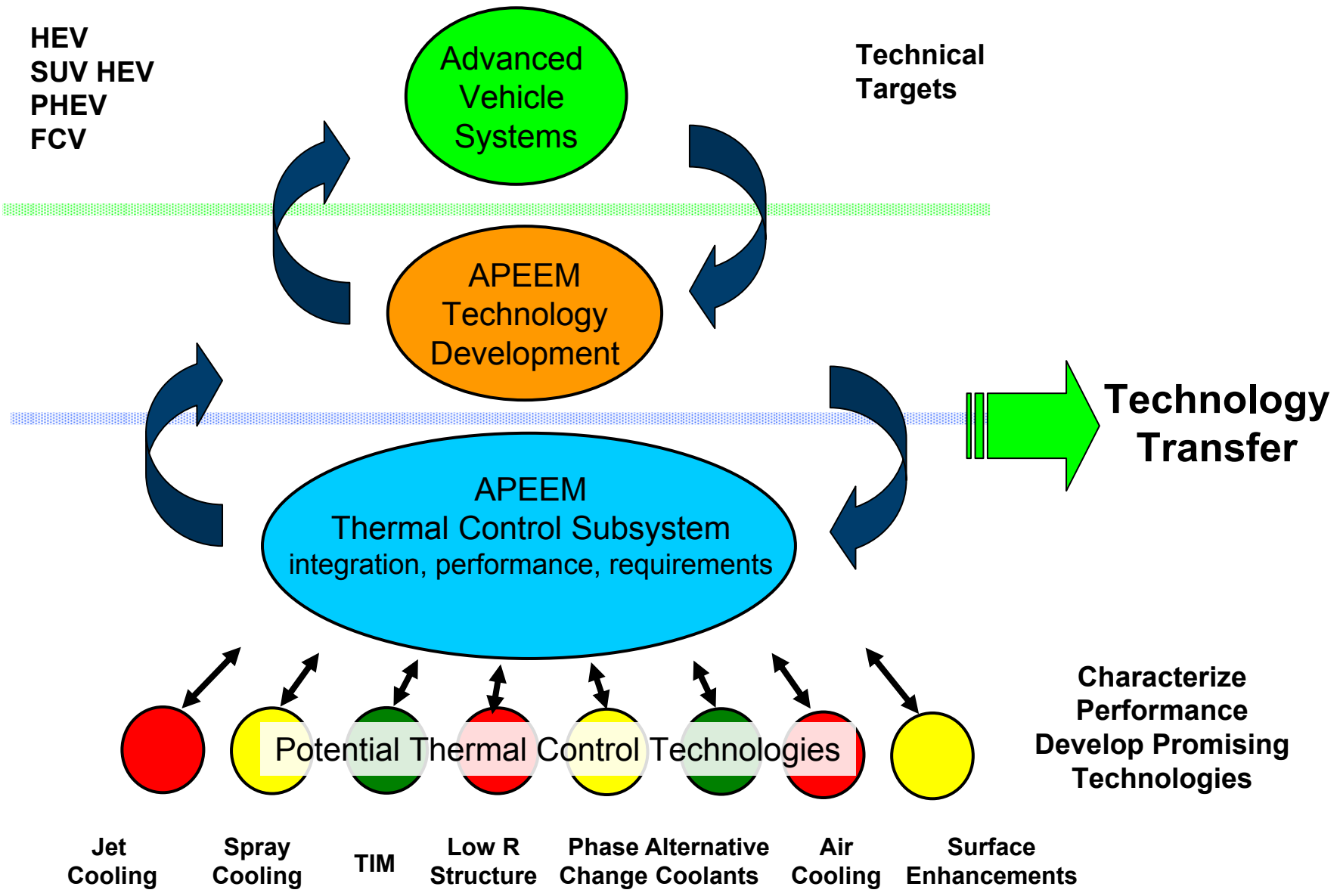
Reduce Thermal Resistance

- advanced TIM materials
- low R IGBT structure

T_H

Increase maximum allowable temperature

- PE materials development



FY08 Thermal Control R&D Projects

1. Power Electronic Thermal System Performance and Integration
 - ***Kevin Bennion, NREL***
2. Characterization and Development of Advanced Heat Transfer Technologies
 - ***Thomas Abraham, NREL***
3. Research and Development of Air Cooling Technology for Power Electronics Thermal Control
 - ***Desikan Bharathan, NREL***
4. Direct-Cooled Power Electronics Substrate
 - ***Randy Wiles, ORNL***
5. Advanced Thermal Interface Materials for Power Electronics
 - ***Sreekant Narumanchi, NREL***
6. Thermal Stress and Reliability for Advanced Power Electronics and Electric Machines
 - ***Michael O'Keefe, NREL***

Questions

